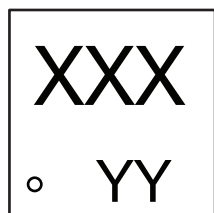
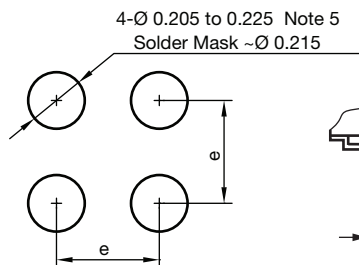
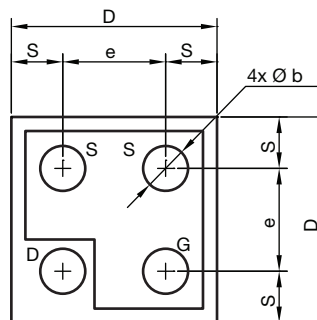


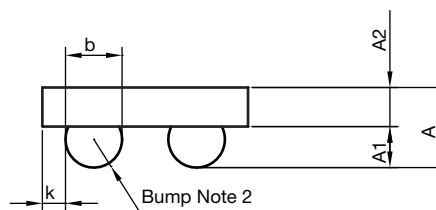
MICRO FOOT®: 4-Bump (0.8 mm x 0.8 mm, 0.4 mm Pitch) With 0.200 mm Pad



Mark on Backside of die



Note 4



Notes

- (1) Laser mark on the backside surface of die
- (2) Bumps are 95.5 % Sn, 3.8 % Ag, 0.7 % Cu
- (3) "i" is the location of pin 1
- (4) "b1" is the diameter of the solderable substrate surface, defined by an opening in the solder resist layer solder mask defined.
- (5) Non-solder mask defined copper landing pad.

DIM.	MILLIMETERS ^a			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.310	0.350	0.390	0.0122	0.0138	0.0154
A1	0.126	0.150	0.170	0.0050	0.0059	0.0067
A2	0.184	0.200	0.220	0.0072	0.0079	0.0087
b	0.200	0.220	0.240	0.0078	0.0086	0.0094
b1	0.200			0.0078		
e	0.400			0.0157		
S	0.160	0.180	0.200	0.0062	0.0070	0.0078
D	0.720	0.760	0.800	0.0283	0.0299	0.0314
K	0.040	0.070	0.100	0.0015	0.0027	0.0039

Note

- a. Use millimeters as the primary measurement.

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